



Material Content Data Sheet



Sales Product Name	BSF030NE2LQ			Issued		29. August 2013		
MA#	MA000961536							
Package	MG-WDSO-N-2-3			Weight*		49.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.664	3.37	3.37	33748	33748
leadframe	non noble metal	copper	7440-50-8	45.114	91.52	91.52	915185	915185
leadfinish	non noble metal	nickel	7440-02-0	0.115	0.23		2327	
	noble metal	silver	7440-22-4	0.456	0.93	1.16	9254	11581
plating	non noble metal	nickel	7440-02-0	0.077	0.16	0.16	1571	1571
glue	plastics	epoxy resin	-	0.103	0.21		2088	
	noble metal	silver	7440-22-4	0.632	1.28	1.49	12825	14913
solder	non noble metal	copper	7440-50-8	0.005	0.01		106	
	noble metal	silver	7440-22-4	0.031	0.06		634	
	non noble metal	tin	7440-31-5	1.006	2.04	2.11	20404	21144
passivation	plastics	epoxy resin	-	0.092	0.19	0.19	1858	1858
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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